

ABSTRACT

A semiconductor chip package includes an IC chip and a tape circuit substrate. The
5 tape circuit substrate has a base film and a plurality of beam leads formed on the base film.
One end portion of each beam lead extends from the base film, and the extended portion has a
wavy portion. The wavy portion can be, for example, semicircular shaped, an S-shaped, or a
zigzag shaped. The IC chip has chip pads formed on a top surface thereof. The beam lead is
bonded to the chip pad through an inner lead bonding (ILB) process. During the ILB process,
10 the wavy portion disperses the stress produced in the beam lead. Therefore, a crack or a break
of the beam lead due to the stress can be effectively prevented, improving interconnection
reliability between the IC chip and the tape circuit substrate.